

# DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

☒ Original   ☐ Supplemental   ☐ Substitute   ☐ PCT   ☐ Design

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**TITLE:** SEMICONDUCTOR DEVICE INCLUDING AIR GAP BETWEEN SEMICONDUCTOR SUBSTRATE AND L-SHAPED SPACER AND METHOD OF FABRICATING THE SAME

of which is described and claimed in:

☒ the attached specification, *or*

☐ the specification in the application Serial No. \_\_\_\_\_ filed \_\_\_\_\_, and with amendments through \_\_\_\_\_ (if applicable), *or*

☐ the specification in International Application No. \_\_\_\_\_ filed \_\_\_\_\_, and as amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose information of which I am aware which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United State Code, §119 (and §172 if this application is for a Design) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application n which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Republic of Korea	2003-55897	August 12, 2003	YES

I hereby claim the benefit under Title 35, United States code, §120 and §119(e) of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED


***Kindly direct all correspondence to:***

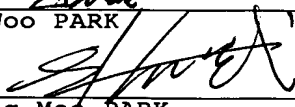
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POST OFFICE ADDRESS	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE

I further declare that all statements made herein of my own knowledge are true, and that all statements on information and believe are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1<sup>st</sup> Inventor  Date March 15, 2004  
Ho-Woo PARK

2<sup>nd</sup> Inventor  Date Mar. 15, 2004  
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6<sup>th</sup> Inventor \_\_\_\_\_ Date \_\_\_\_\_

Applicant's Ref. SPX200306-0024US Attorney Docket No. SEC.1135